



“ The DUO PLUS product has undergone a technological evolution with the launch of its new 28nm platform making it more efficient and competitive in the market ”

## **DUO PLUS 28**

**A63**

**The essence of payments**

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# Advantis

“1,500 million cards issued in the world have the Advantis technology, with a strong presence in America and Europe”

## Leadership and Reliability



“Advantis is a high-security EMV chip that has been used in smart cards for over 30 years”

**Advantis** is a multi-application issuance solution EMV chip, which enables the processing of a financial transactions, through different smart devices.

**Advantis Contactless** provides a high level of service within environments in which transaction speed and secure data storage are key factors.

**Advantis Contactless DUO PLUS 28** includes the MasterCard application and two VISA applications: VSDC281G1 applet, implemented by Visa, and an Advantis applet with extended functionality.



# Advantages

*“Provides simplicity and flexibility including the VISA and MasterCard applications in a same chip”*

## Freedom of choice

*“Advantis Contactless DUO PLUS 28 is developed on a more optimized technology that allows us to offer a more competitive product while providing all the security of an EMV chip”*



### ○ **SIMPLICITY**

Advantis Contactless DUO PLUS 28 is based on standards international Global Platform and CPS facilitating the qualification of the product.

### ○ **MULTI-BRAND**

Advantis Contactless DUO PLUS 28 includes the VISA application and MasterCard on a single chip and allows issuers have a single technology regardless of the financial application used.

### ○ **MULTI-PROVIDER**

Advantis issuing technology is compatible with different suppliers of chips, antennas, bureaux of perso... providing a greater possibility of choice and competitive offer.

### ○ **SUPPORT**

We offer customers support throughout the qualification process, providing perso manuals, profile development, and a sample kit to test the product.



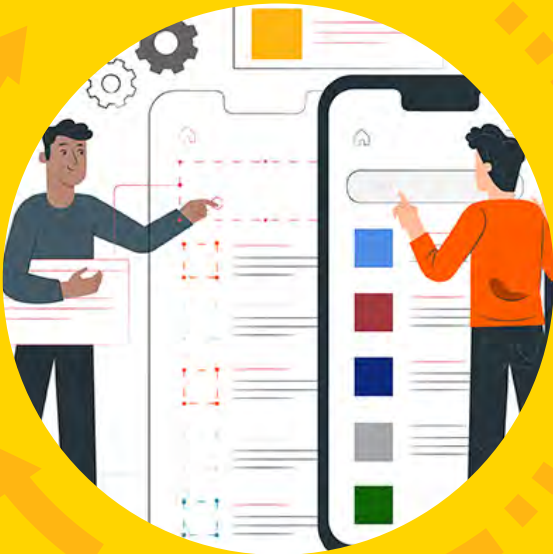
**COIL ON MODULE  
PACKAGING**

**LONG LASTING  
SOLUTION**



**TIME-TO-MARKET:  
VISA & MASTERCARD**

**CPS PERSONALIZATION**



# Specifications

## Technical Specifications

### TECHNICAL SPECIFICATIONS

Operating System Technology Reference	Advantis Contactless DUO PLUS 28 ADV63
Global Platform	Javacard 3.0.5 Classic, Global Platform 2.3.1
Personalization	EMV CPS v1.1
NVM Flash memory	23 kbytes
Antenna	Coil on Module

### APPLICATIONS

VISA	VIS1.5.4 - VSDC 2.8.1G1 Advantis VISA Applet (VIS 1.5.4 VCSP2.1.3 MA2.1)
MasterCard	M/Chip Advance MCADP v1.2.3

### CERTIFICATIONS

VISA	November 30, 2034
MasterCard	May 10, 2026

### FEATURES

EMV protocol	Contact protocol=ISO 7816 T=1 and T=0 Contactless=ISO 14443 Type A
Cryptography	DDA/CDA

### CHIP FEATURES

Chip	SLJ26P (28nm Flash technology)
Chip manufacturer	Infineon Technologies AG

**Advantis**



# The essence of payments



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